

Filename: PMP6659_RevC_bom.xls						
Date: 05/21/2015						
PMP6659 REV C BOM						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C18	47pF	Capacitor, Ceramic, 50V, C0G, 10%	603	Std	Std
1	C32	100pF	Capacitor, Ceramic, 25V, C0G, 10%	603	Std	Std
1	C13	330pF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C6, C21	1000pF	Capacitor, Ceramic, 100V, C0G, 10%	603	Std	Std
4	C1, C2, C3, C4	0.01uF	Capacitor, Ceramic, 100V, X7R, 10%	603	Std	TDK
1	C33	0.033uF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
2	C22, C28	0.1uF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
6	C7, C12, C23, C24, C36, C37	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	805	Std	TDK
1	C31	0.15uF	Capacitor, Ceramic, 16V, X7R, 10%	603	Std	Std
2	C30, C38	1uF	Capacitor, Ceramic, 25V, X7R, 10%	805	Std	Std
2	C25, C26	2.2uF	Capacitor, Ceramic, 16V, X7R, 10%	805	Std	Std
3	C10, C11, C19	2.2uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	C3225X7R2A225K	TDK
3	C8, C14, C15	22uF	Capacitor, Ceramic, 25V, X7R, 10%	1210	Std	Std
1	C5	1000pF	Capacitor, Ceramic, 2KV, X7R, 10%	1812	C4532X7R3D102K	TDK
1	C17	4700pF	Capacitor, Ceramic, 2KV, X7R, 10%	1812	C4532X7R3D472K	TDK
1	C16	39uF	Capacitor, OS CON, 16V, 50 milliohm, 20%	6x6mm	16SVP39M	Sanyo
1	C9	22uF	Capacitor, Aluminum Electrolytic, 100V, 20%	8x10.2mm	EEEFK2A220PF	Panasonic
4	C27, C29, C34, C35	220uF	Capacitor, Aluminum Electrolytic, 50V, 20%	10x10.2mm	EEEFK1H221P	Panasonic
1	D1		Diode, SMT TVS 400W, 4.3-A, 58-V	SMA	SMAJ58A	Diodes
4	D10, D18, D19, D20		Diode, Schottky, 200mA, 30V, 200mW	SOD-323	BAT54HT1	On Semi
1	D13	10V	Diode, Zener, 200mW, 10V	SOD-323	BZT52C10S	Diodes, Inc
2	D14, D15		Diode, Ultra Fast, 6A, 200V	PowerDI-5	PDU620	Diodes, Inc
0	D100	DNP	Diode, Schottky, 100V, 8A	TO-277A[SMPC]	V8P10	Vishay
2	D16, D17	5.1V	Diode, Zener, 200mW, 5.1V	SOD-323	BZT52C5V1S	Diodes, Inc
2	D2, D3		Bridge Rectifier, 100V, 1.5A, Glass Passivated, SMD	DF-S	DF1501S	Diodes
1	D5		Diode, Rectifier, Ultra-fast, 3A, 150V	SMB	ES3CB	Diodes, Inc
4	D6, D7, D9, D11		Diode, Schottky, 2A, 60V	SMA	B260A	Diodes, Inc
4	D4, D8, D12, D21		Diode, Switching, 100V, 200mA, 400mW,	SOD-123	MMSD4148	On Semi
2	FB1, FB2		Bead, Ferrite, 1.5A, 15 Ohms	805	MMZ2012R150A	TDK
2	J1, J2		Connector, Jack, Modular, 8 POS	0.705 x 0.820 inch	520252-4	AMP
3	J3, J4, J5		Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	J6		Header, Male 2-pin, 100mil spacing, (36-pin strip)	0.100 inch x 2	PTC36SAAN	Sullins
1	L1	3.3uH	Inductor, SMT, 3.95A, 20 milliohms	7.3x7.3mm	MSS7341-332ML	Coilcraft
1	L2	1uH	Inductor, SMT, 1.8A, 42 milliohm	4x4mm	LPS4018-102X	Coilcraft
1	L3	217uH	Inductor, Common Mode, 2.85A, 20 milliohms	11.43x13.97mm	CMS3-6-R	Cooper-Bussmann

1	L4	205uH	Inductor, Common Mode, 850mA, 186 milliohms	7.2x9.4mm	CMS1-14-R	Cooper-Bussmann
1	Q1		MOSFET, NChan, 150V, 9.6A, 18 milliohm	Power 56	FDMS86200	Fairchild
2	Q2, Q3		Trans, PNP, 40V, 200mA, 225mW	SOT23	MMBT3906LT1G	On Semi
1	Q4		MOSFET, NChan, 100V, 6A, 34 milliohm	Power 56	FDMS86105	Fairchild
1	Q5		Trans, NPN, 40V, 200mA, 225mW	SOT23	MMBT3904LT1G	On Semi
1	Q6		MOSFET, N-ch, 60V, 2.8A , 0.11 Ohms	SOT-223	FQT13N06L	Fairchild
3	R7, R35, R39	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R17	63.4	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R1, R2, R3, R4	75	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R22	301	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	1K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R20, R25	2K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R28	2.61K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R6, R31	4.99K	Resistor, Chip, 1/16W, 1%	603	Std	Std
3	R21, R23, R26	10K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R16, R27	24.9K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R33	37.4K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R19	69.8K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R18	75K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R9, R15	200K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R32	237K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R29	422K	Resistor, Chip, 1/16W, 1%	603	Std	Std
0	R13, R24, R30	DNP	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R12	20	Resistor, Chip, 1/10W, 5%	805	Std	Std
1	R5	39K	Resistor, Chip, 1/4W, 5%	1206	Std	Std
1	R10	0.1	Resistor, Chip, 1W, 5%	2512	Std	Std
1	R11	10	Resistor, Chip, 1W, 5%	2512	Std	Std
1	R14	51	Resistor, Chip, 1W, 5%	2512	Std	Std
1	T1		Transformer, High Power PoE	S0 14 Wide	ETH1-230LD	Coilcraft
1	T2		Transformer, Flyback, 45uH	0.810 X 1.181 inch	MA5281-BL	Coilcraft
1	TP1		Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
1	U3		IC, Photocoupler, 80-160% CTR	MF4	TCMT1107	Vishay
1	U5		IC, Photocoupler, 200-400% CTR	MF4	TCMT1109	Vishay
1	U4		IC, Precision Adjustable Shunt Regulator	SOT23-5	TL431ACDBVR	TI
1	U2		IC, IEEE 802.3at PoE Interface/Isolated Converter Controller	PWP20	TPS23756PWP	TI

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